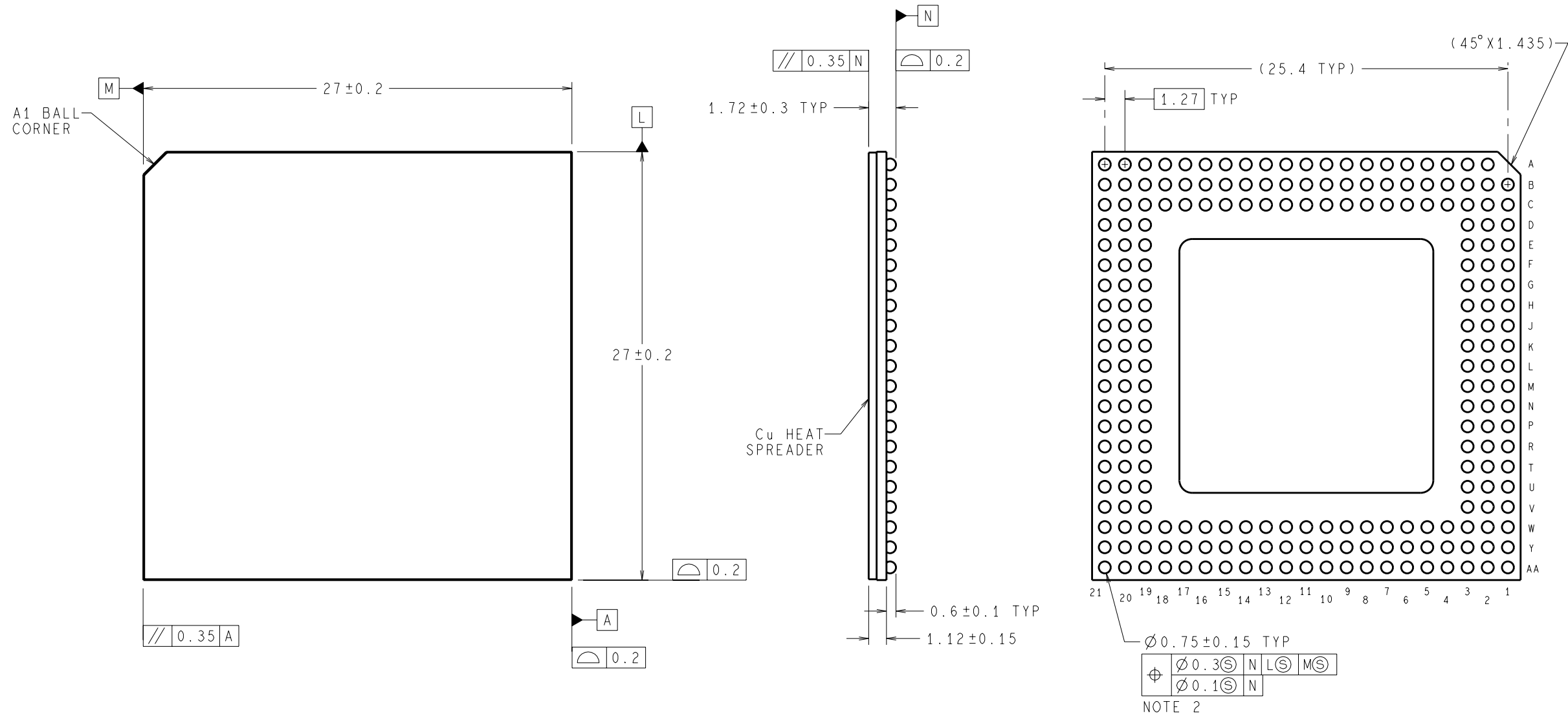


REVISIONS				
LTR	DESCRIPTION	E.C.N.	DATE	BY/APP'D
A	RELEASE TO DOCUMENT CONTROL	12466	05/12/2000	MS/VG
B	REVISE TITLE; BODY TOL 0.2 WAS 0.15; REMOVE HEAT SPREADER & BT THK'S DIM'S; PKG HEIGHT TOL 0.3 WAS 0.2; ADD DIM 1.12 0.15.	144	11/17/2000	MS/AP



DIMENSIONS ARE IN MILLIMETERS

NOTES: UNLESS OTHERWISE SPECIFIED

- SOLDER BALL COMPOSITION: Sn 63%, Pb 37%.
- DIMENSION IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM N.
- REFERENCE JEDEC REGISTRATION MO-151, VARIATION -1.27.

APPROVALS		DATE	National Semiconductor		
DRAWN MARTA SUCHY		05/12/2000	2900 Semiconductor Dr., Santa Clara, CA 95052-8090		
DFTG. CHK. THANH LEQUANG		11/17/2000	EBGA, 27 X 27 X 1.72mm, 215 BALL, 1.27mm PITCH		
ENGR. CHK. ANINDYA PODDAR		11/17/2000			
		SCALE	SIZE	DRAWING NUMBER	REV
		N/A	C	(SC)MKT-UCM215A	B
DO NOT SCALE DRAWING				SHEET 1 of 1	